

Features

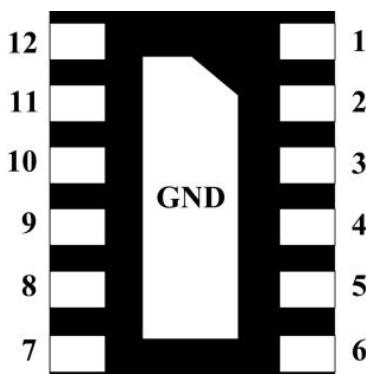
- EMI symmetrical (I/O) low-pass filter (6 channels)
- High efficiency in EMI filtering: -30 dB at frequencies from 900 MHz to 1.8 GHz
- Very low PCB space consumption: 2.4mm x 1.5mm
- Very thin package: 0.55mm max
- High efficiency in ESD suppression (IEC 61000-4-2 level 4)
- Surge clamping voltage: 11.0V@4.0A
- High reliability offered by monolithic integration
- Lead-free package
- Each I/O pin can withstand over 1000 ESD strikes for $\pm 25\text{kV}$ contact discharge

Description

TFR0506LX is a 6-line, highly integrated device designed to suppress EMI /RFI noise in all systems exposed to electromagnetic interference.

This filter incorporates ESD & Surge protection circuitry, which prevents damage to the application when subjected to 8/20 μs surges up to 4.0A and ESD discharges up to 25kV on each I/O pin. It complies with IEC 61000-4-2 (ESD), Level 4 ($\pm 8\text{kV}$ contact, $\pm 15\text{kV}$ air discharge).

Pin Configuration



DFN2415-12L
(Bottom View)



DFN2415-12L
(Top View)

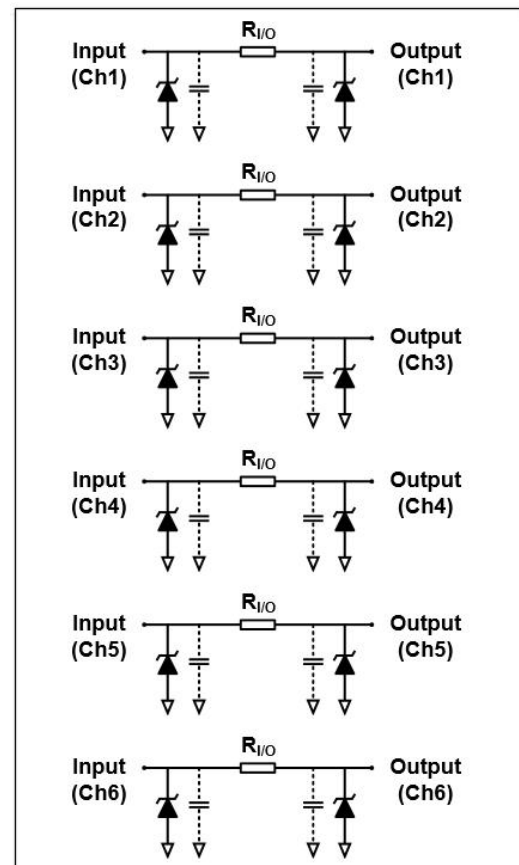
Applications

- LCD and camera for mobile phones
- SD Memory Card Interfaces
- Computers and printers
- Communication systems
- MCU boards

Mechanical Characteristics

- Package: DFN2415-12L
- Marking: Part number
- Packaging: Tape and Reel
- ROHS compliant
- Moisture Sensitivity Level (MSL Level-1)

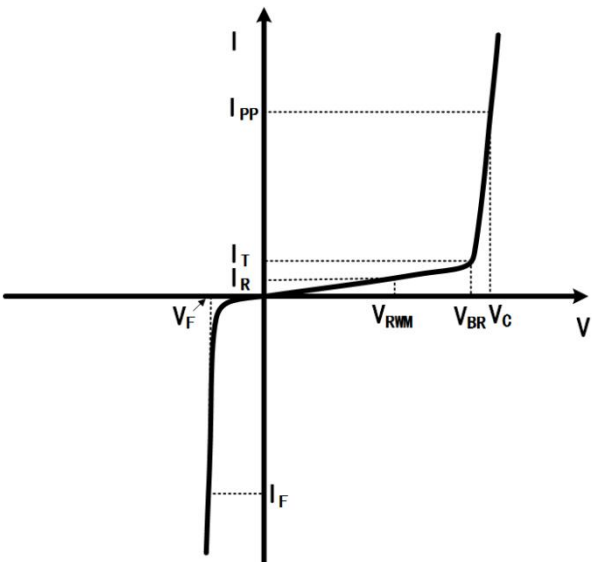
Circuit Diagram



Absolute Maximum Rating

Symbol	Parameter	Value	Units
I_{PP}	Peak Pulse Current (8/20 μ s)	4.0	A
P_{PK}	Peak Pulse Power (8/20 μ s)	40	W
V_{ESD}	ESD per IEC61000-4-2 (Air) ESD per IEC61000-4-2 (Contact)	± 25 ± 25	kV
T_{OPT}	Operating Temperature	-55/+125	°C
T_{STG}	Storage Temperature	-55/+150	°C

Electrical Characteristics (T = 25°C)

Symbol	Parameter	Diagram
V_{RWM}	Nominal Reverse Working Voltage	
I_R	Reverse Leakage Current @ V_{RWM}	
V_{BR}	Reverse Breakdown Voltage @ I_T	
I_T	Test Current for Reverse Breakdown	
I_F	Forward Current	
V_F	Forward Voltage @ I_F	
I_{PP}	Maximum Peak Pulse Current	
V_C	Clamping Voltage @ I_{PP}	
C_{ESD}	Parasitic Capacitance	
R_{dyn}	Dynamic Resistance	
$R_{I/O}$	Series resistance between Input&Output	
α_{IL}	Insertion Loss	
f _{-3db}	Cut-off frequency at -3dB	

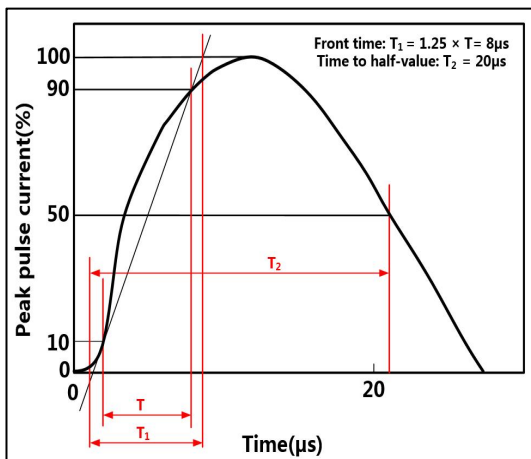
Symbol	Test Condition	Minimum	Typical	Maximum	Units
V_{RWM}				5.0	V
I_R	$V_{RWM} = 5.0V, T = 25^\circ C$ Between I/O and GND		10	100	nA
V_{BR}	$I_T = 1mA$ Between I/O and GND	5.5	7.7		V
V_F	$I_F = 1mA$ Between GND and I/O		0.85		V
V_C	$I_{PP} = 4.0A, t_p = 8/20\mu s$ Between IO and GND		11		V
V_C	$I_{PP} = 8A, t_p = 100ns^{(1)}$ Between I/O and GND		10		V
	$I_{PP} = 16A, t_p = 100ns^{(1)}$ Between I/O and GND		13		V

Symbol	Test Condition	Minimum	Typical	Maximum	Units
R_{dyn}	$I_{PP} = 12.0A$, $t_p = 100ns^{(1)}$ Between I/O and GND		0.35		Ω
$R_{I/O}$	Between Input and Output		60		Ω
C_{ESD}	$V_R = 0V$, $f = 1MHz$ Between I/O and GND		50		pF
α_{IL}	$f = 0.9GHz \sim 1.8GHz$		-30		dB
f_{-3db}	$\alpha_{IL} = -3db$ Between Input and Output		0.1		GHz

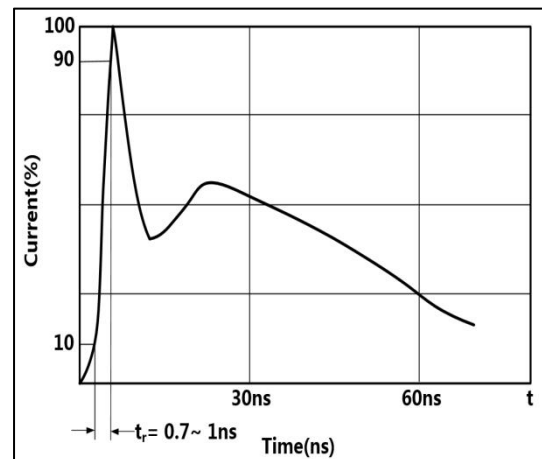
Notes:(1)Measurements performed using a 100ns Transmission Line Pulse(TLP) system.

Typical Performance Characteristic

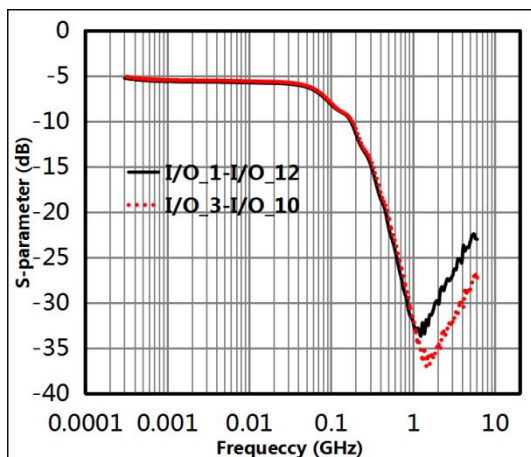
8/20 μs surge waveform (IEC61000-4-5)



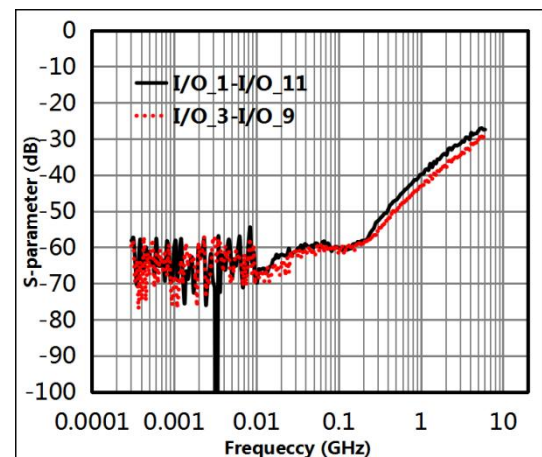
Contact discharge current waveform (IEC61000-4-2)



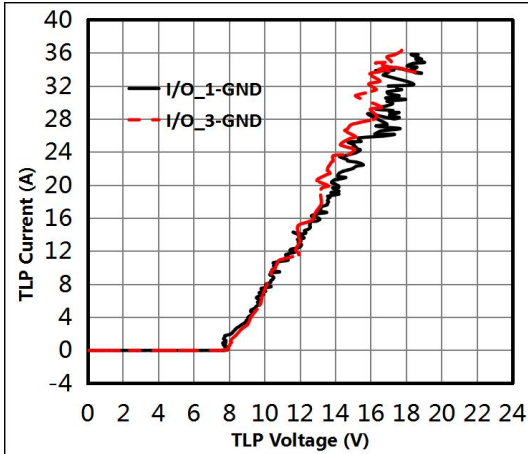
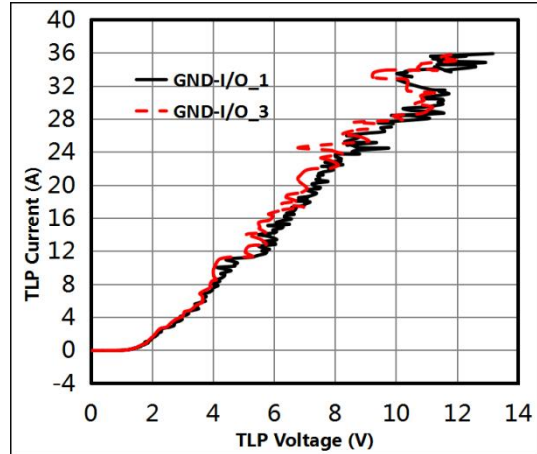
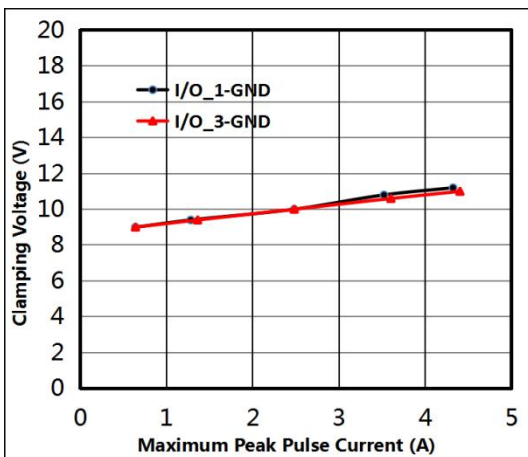
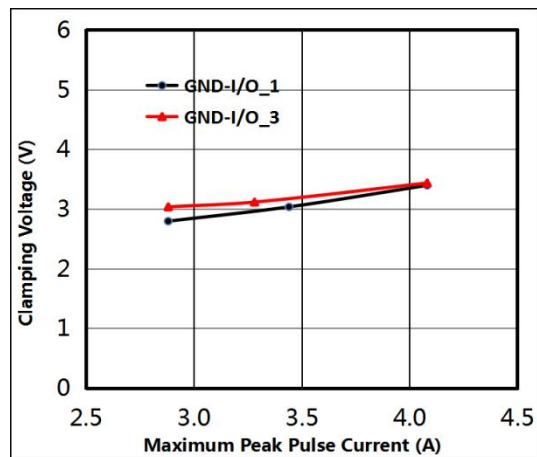
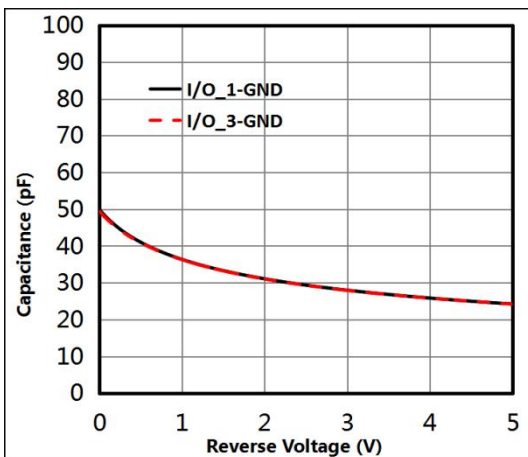
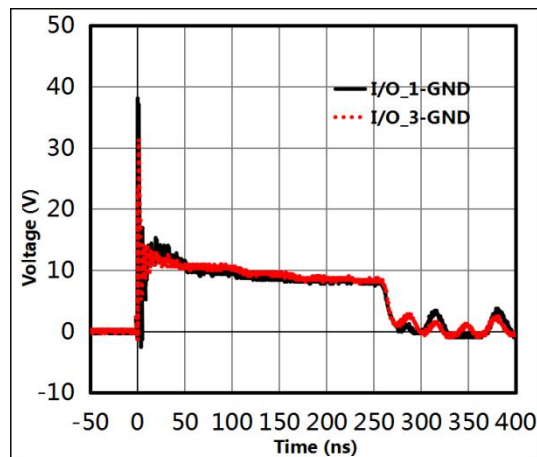
Insertion loss of Input to Output



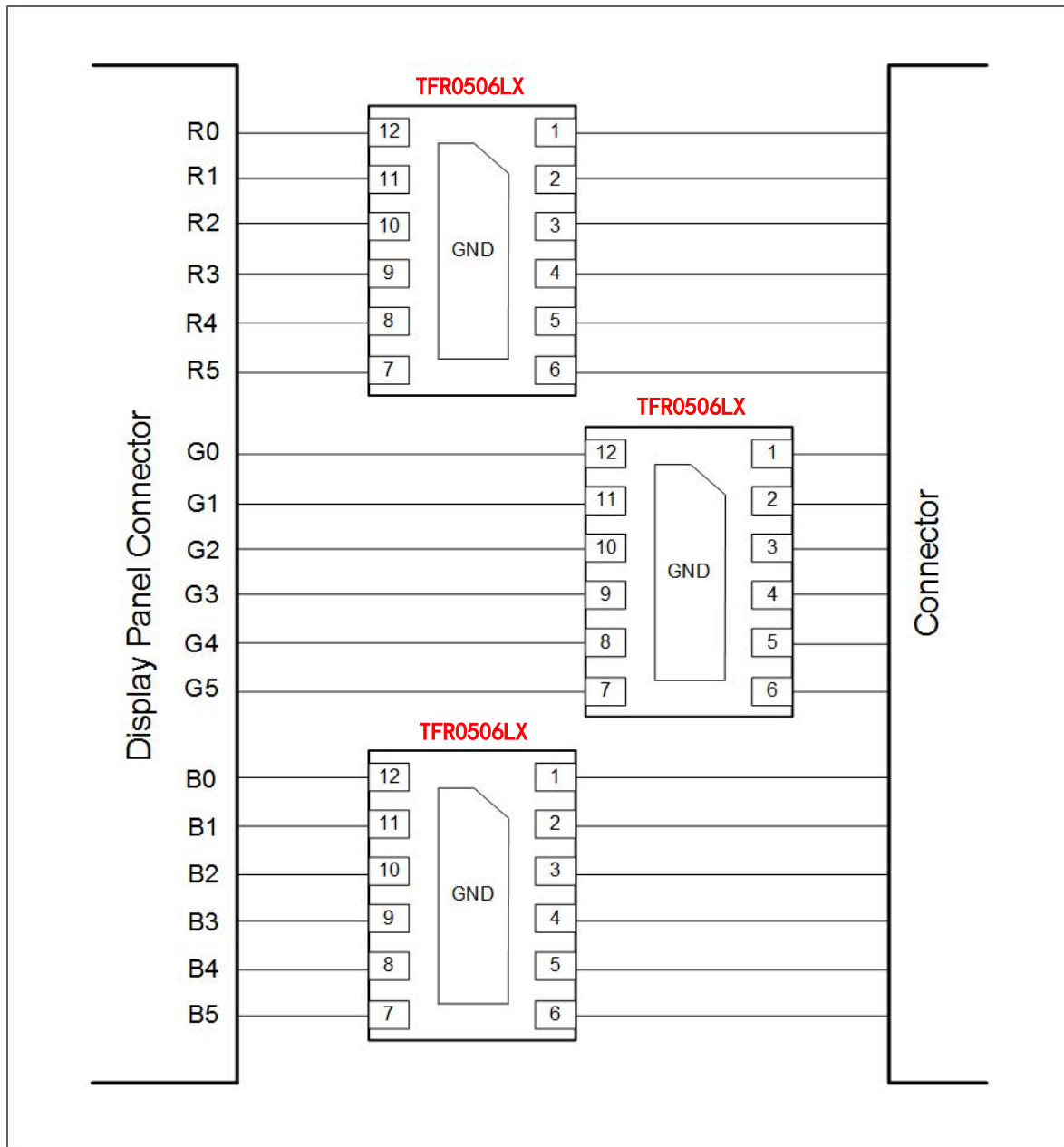
Analog cross talk of Input to Output



Typical Performance Characteristics

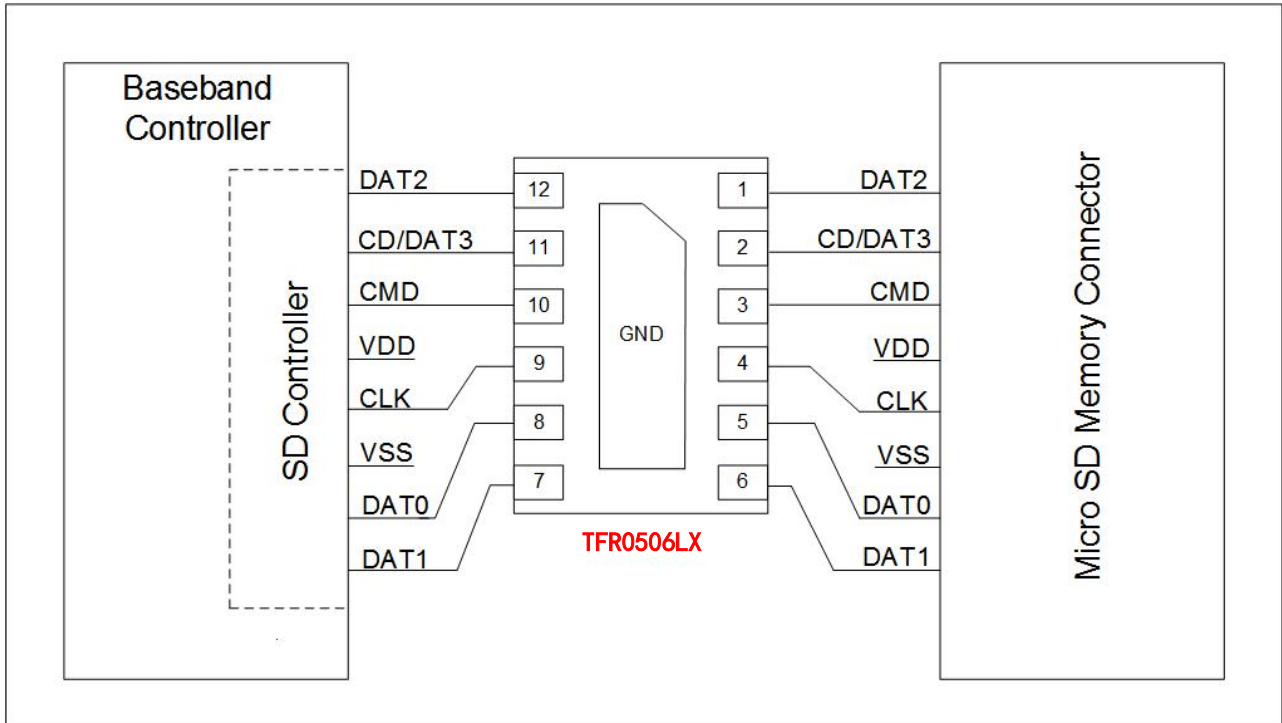
TLP Measurement of I/O to GND

TLP Measurement of GND to I/O

8/20us Current I/O to GND

8/20us Current GND to I/O

Capacitance vs Reverse Voltage of I/O to GND

+8kV Contact IEC Waveform of I/O to GND


Application Information



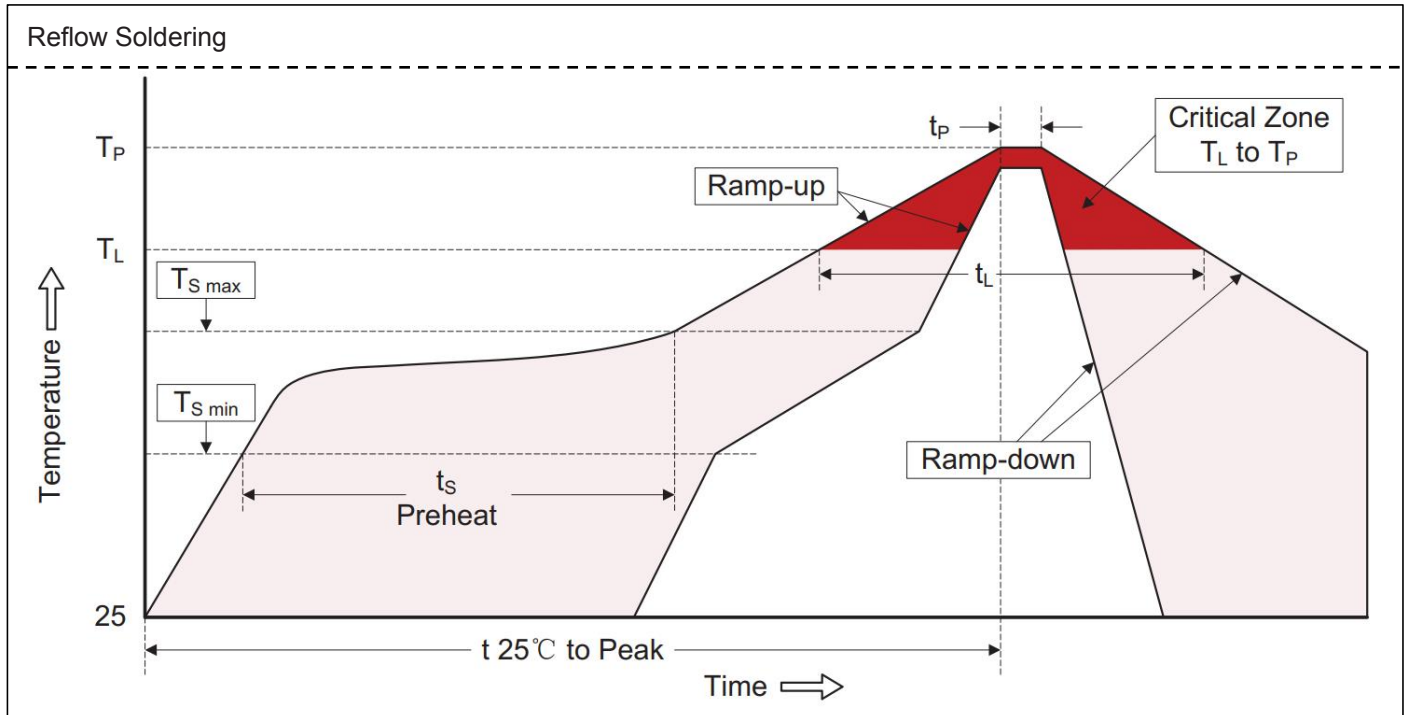
Display Panel

Application Information



Micro SD Memory

Recommended Soldering Conditions

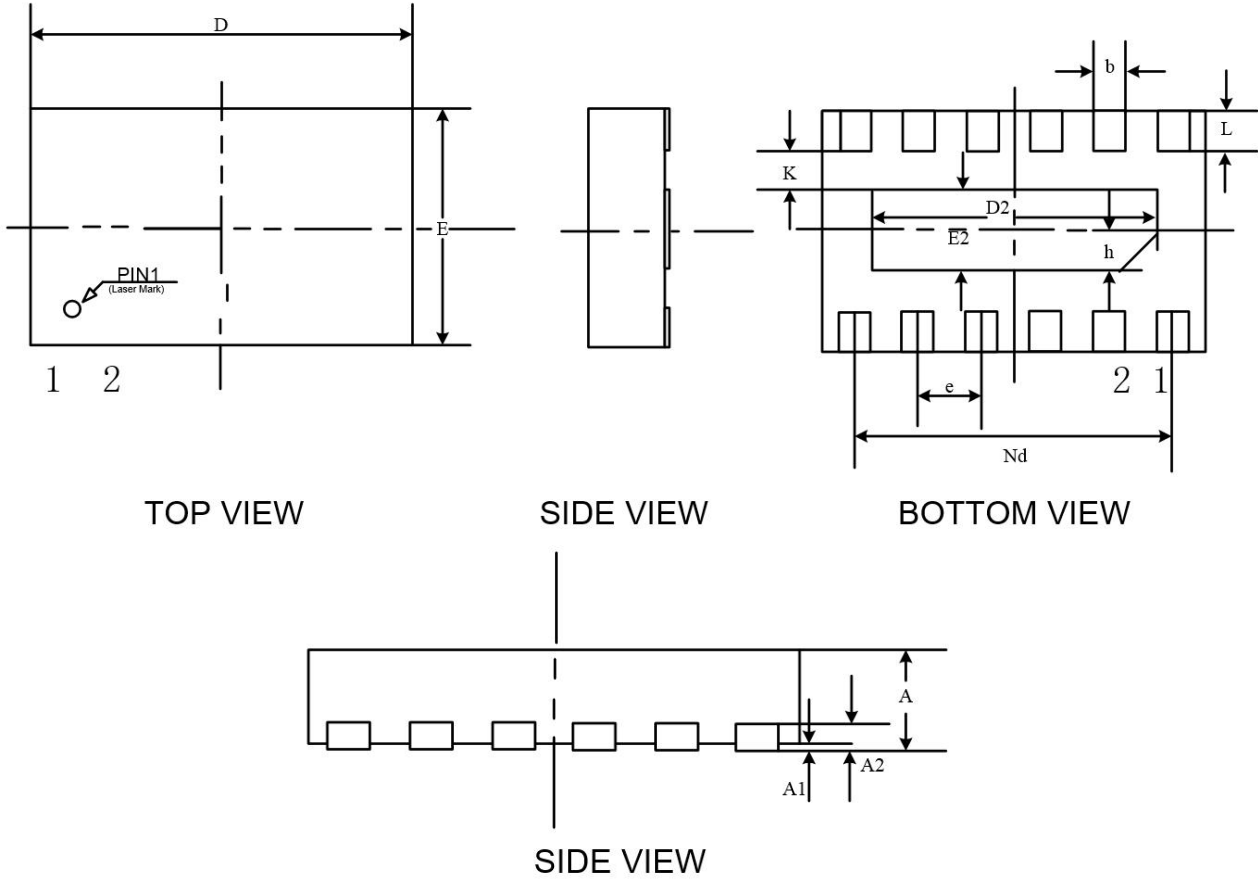


Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-down Rate	6°C/second max
Time 25°C to Peak Temperature	8 minutes max

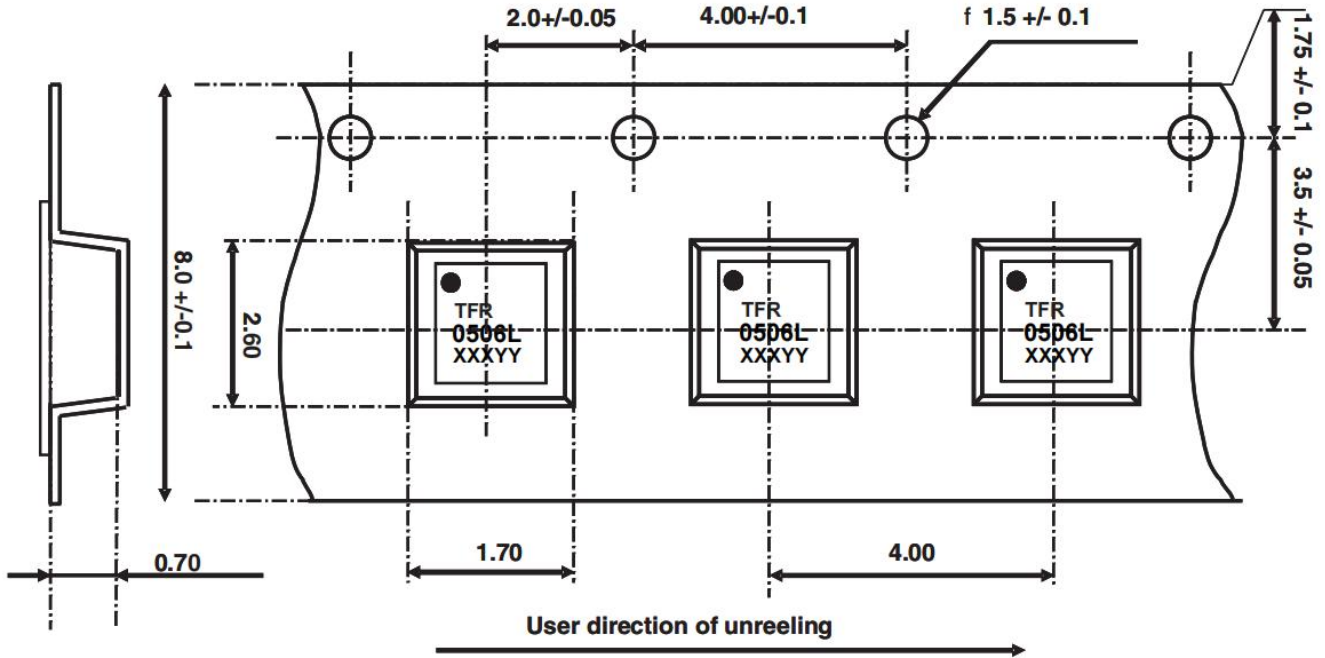
Package Outline

■ DFN2415-12L



Mechanical dimensions/mm			
SYMBOL	MIN	NOMINAL	MAX
A	0.45	0.5	0.55
A1	0	0.02	0.05
A2	0.127 REF		
b	0.15	0.2	0.25
D	2.3	2.4	2.5
D2	1.7	1.8	1.9
Nd	2.0 BSC		
e	0.4 BSC		
E	1.4	1.5	1.6
E2	0.4	0.5	0.6
L	0.2	0.25	0.3
h	0.2	0.25	0.3
K	0.2	0.25	0.3

Tape and Reel Specification



Marking Codes



Note:

- (1) "TFR" is part number, fixed.
- (2) "0506L" is part number, fixed.
- (3) "XXXYY" is the identification number.

Ordering Information

Part Number	Working Voltage	Quantity Per Reel	Reel Size
TFR0506LX	5.0V	3,000	7 Inch

Ordering information scheme

